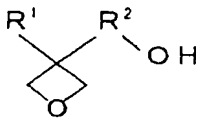
AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A curable polyester having at least one oxetanyl group at the molecular ends.

2. (original): The curable polyester according to claim 1, which is obtained by transesterification of a compound (A) represented by the following formula (1):

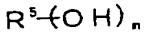


Formula (1)

(wherein R^1 represents a hydrogen atom or an alkyl group having 1 to 6 carbon atoms, and R^2 represents an alkylene group having 1 to 6 carbon atoms), a compound (B) represented by the following formula (2):

Formula (2)

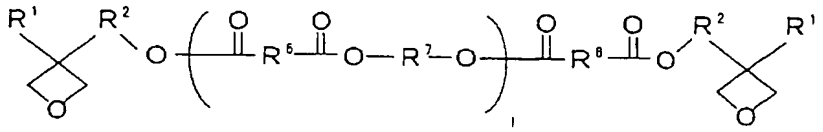
(wherein R^3 represents a di- to tetra-valent organic group, R^4 represents an alkyl or alkenyl group having 1 to 6 carbon atoms, and n represents an integer of 2 to 4) and a compound (C) represented by the following formula (3):



Formula (3)

(wherein R^5 represents a di- to eicosa-valent organic group, and m represents an integer of 2 to 20).

3. (currently amended): A curable polyester having an oxetanyl group at both molecular ends according to claim 1 ~~or 2~~, which has a structure represented by following formula (4):

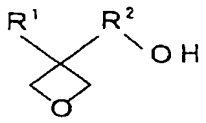


Formula (4)

(wherein R^1 represents a hydrogen atom or an alkyl group having 1 to 6 carbon atoms, R^2 represents an alkylene group having 1 to 6 carbon atoms, R^6 and R^7 each represents a divalent organic group, and l represents an integer of 0 to 50).

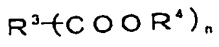
4. (currently amended): A cured product obtained by curing the curable polyester of claim 1~~any one of claims 1 to 3~~.

5. (original): A process for preparing a curable polyester, which comprises transesterifying a compound (A) represented by the following formula (1):



Formula (1)

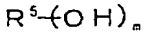
(wherein R^1 represents a hydrogen atom or an alkyl group having 1 to 6 carbon atoms, and R^2 represents an alkylene group having 1 to 6 carbon atoms), a compound (B) represented by the following formula (2):



Formula (2)

(wherein R^3 represents a di- to tetra-valent organic group, R^4 represents an alkyl or alkenyl group having 1 to 6 carbon atoms, and n represents an integer of 2 to 4) and a compound (C) represented by the following formula (3):

Formula (3)



(wherein R^5 represents a di- to eicosa-valent organic group, and m represents an integer of 2 to 20).

6. (currently amended): A resist composition comprising the curable polyester of claim 1~~any one of claims 1 to 3~~.

7. (original): The resist composition according to claim 6, wherein the content of the curable polyester is from 3 to 50% by weight based on the resin component of the composition.

8. (currently amended): An ink comprising the resist composition of claim 6~~ or 7~~ and a colorant.

9. (currently amended): A method for curing a resist composition, which comprises, performing pattern printing of the resist composition of claim 6~~ or 7~~ on a substrate, and curing a curable polyester having at least one oxetanyl group at the molecular ends~~of any one of claims 1 to 3~~ while melting with heating.

10. (currently amended): The method for curing a resist composition according to claim 9, wherein a heat melting or heat curing temperature of the curable polyester~~ of any one of claims 1 to 3~~ is from 40 to 250°C.

11. (currently amended): A heat cured product of the resist composition of claim 6 ~~or 7~~.

12. (currently amended): An insulation protective film comprising a cured product of the resist composition of claim 6 ~~or 7~~.

13. (currently amended): An interlayer insulation film comprising a cured product of the resist composition of claim 6 ~~or 7~~.

14. (original): A print circuit board comprising the insulation protective film of claim 12.

15. (original): A print circuit board comprising the interlayer insulation film of claim 13.

16. (currently amended): A jet printing ink composition comprising the curable polyester of claim 1 ~~any one of claims 1 to 3~~.

17. (currently amended): The jet printing ink composition according to claim 16, wherein the content of the curable polyester ~~of any one of claims 1 to 3~~ is from 3 to 50% by weight based on the resin component of the composition.

18. (currently amended): The jet printing ink composition according to claim 16, which comprises an epoxy resin (B) as the resin component other than the curable polyester ~~of any one of claims 1 to 3~~.

19. (original): The jet printing ink composition according to claim 16, wherein resins in the essential component composition are dissolved in a solvent (C) or dispersed in the solvent (C).

20. (original): The jet printing ink composition according to claim 19, wherein the solvent (C) contains a solvent component having a boiling point of 180 to 260°C and a vapor pressure at 20°C of 133 Pa or less in the amount of 60% by weight or more based on the total amount of the solvent.

21. (currently amended): A cured product obtained by drying and heating the solvent (C) of jet printing ink composition of claim 19 ~~or 20~~.

22. (currently amended): A method for curing a jet printing ink composition, which comprises, performing pattern printing on a substrate using the composition of claim 16~~any one of claims 16 to 20~~ according to an ink jet system, and curing the curable polyester ~~of any one of claims 1 to 3~~ while melting with heating.

23. (currently amended): An insulation protective film comprising a cured product of the jet printing ink composition of claim 16~~any one of claims 16 to 20~~.

24. (currently amended): An interlayer insulation film comprising a cured product of the jet printing ink composition of claim 16~~any one of claims 16 to 20~~.

25. (original): A print circuit board comprising the insulation protective film of claim 23.

26. (original): A print circuit board comprising the interlayer insulation film of claim 24.